

Test Research, Inc. (TRI), a leading test and inspection systems provider for the electronics manufacturing industry, returns to Nepcon Japan in 2015 with a powerful and cost-effective one stop solution lineup for inspecting and testing PCB assemblies. Test Research, Inc. invites you to visit **booth EAST 23-28** from **January 14-16** at the **Tokyo Big Sight** for an on-site demonstration of the following inspection systems.



TR7500 SIII 3D AOI

- Total Coverage 2D + 3D AOI
- True 3D Profile Measurement
- Next Generation Easy Programming GUI
- High Performance Design for Automotive and HDI



TR7700 SIII AOI

- High Speed Multi-Phase Inspection
10 μm @ 60 cm^2/sec
15 μm @ 120 cm^2/sec
- New GUI for Easy Programming
- Auto-tuning Intelligent Automated Conveyor System



TR7007Q 3D SPI

- Ultra-high accuracy 3D SPI
- Quad Digital Projector Stop-and-go Inspection system
- Optimized Cost & Performance
- Smart GUI With 5-step Easy Programming
- Closed Loop Integration



TR7007 SII Plus 3D SPI

- Industry Leading Performance 3D SPI
- High Speed Dynamic Imaging Technology
- 200 cm^2/sec @ 15 μm
- Smart GUI With 5-step Easy Programming
- Closed Loop Integration
- Dynamic WBGR Imaging for Fast Fiducial Mark Scanning



TINY SII INLINE ICT

- Automatic Load and Unload
- Integrated Bypass Conveyor
- Conforms to SMEMA Standards
- Fully Electrical Dual Stage Press Unit
- Powerful Boundary Scan Test Solutions
- Easy to Use On-board Programming Software



TR5001T SII TINY ICT

- Multi-ICT Parallel Testing
- Boundary Scan Test
- Serial Device Programming
- Audio Analyzer
- Data Acquisition
- Advanced Analog and Digital Testing with Programmable DUT Power Supplies



TR7600X SII 3D AXI

- Ultra-high-speed Inline 3D X-ray Inspection
- High Resolution Mode for 01005 Components
- BGA, PoP, Press-fit, PTH, QFN, Inspection
- Multiple Resolutions in One Program
- Board Size up to 900 x 460 mm
- Block Scan 3D Slice Imaging